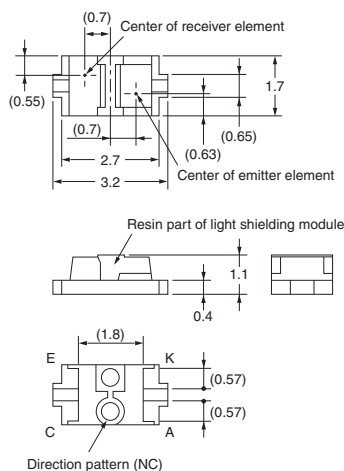


Photomicrosensor (Reflective) EE-SY199

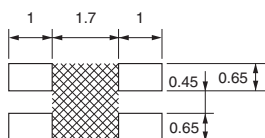
■ Dimensions

Note: All units are in millimeters unless otherwise indicated.



Terminal No.	Name
A	Anode
K	Cathode
C	Collector
E	Emitter

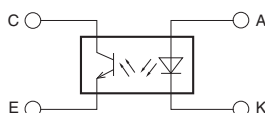
Recommended soldering pattern



Note 1. The shaded portion in the above figure may cause shorting. Do not wire in this portion.

2. The tolerance for the recommended soldering pattern is ± 0.1 mm

Internal Circuit



Unless otherwise specified, the tolerances are ± 0.15 mm.

■ Features

- Ultra-compact model.
- PCB surface mounting type.
- RoHS Compliant.

■ Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Rated value
Emitter	Forward current	I_F 50 mA (see note 1)
	Reverse voltage	V_R 6 V
Detector	Collector–Emitter voltage	V_{CEO} 35 V
	Emitter–Collector voltage	V_{ECO} 6 V
	Collector current	I_C 20 mA
	Collector dissipation	P_C 75 mW (see note 1)
Total Allowable Loss	P_{TOT}	100 mW (see note 1)
Ambient temperature	Operating	T_{opr} -25°C to 85°C
	Storage	T_{stg} -40°C to 100°C
	Max. Reflow soldering	T_{sol} 260°C (see note 2)

Note: 1. Refer to the temperature rating chart if the ambient temperature exceeds 25°C .

2. Complete soldering within 5 seconds. For reflow soldering, use the conditions given in the Precautions section of this datasheet.

■ Ordering Information

Description	Model
Photomicrosensor (reflective)	EE-SY199

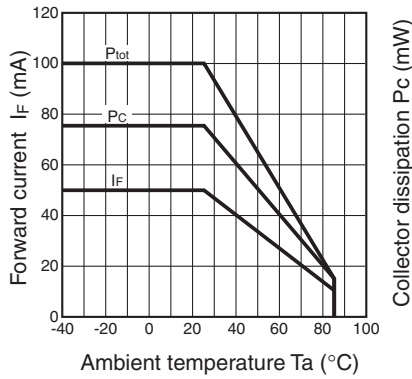
■ Electrical and Optical Characteristics (Ta = 25°C)

Item	Symbol	Value	Condition
Emitter	Forward voltage	V_F 1.2 V typ., 1.4 V max.	$I_F = 20$ mA
	Reverse current	I_R 10 μA max.	$V_R = 6$ V
	Peak emission wavelength	λ_P 950 nm typ.	---
Detector	Light current	I_L 40 μA min., 85 μA typ., 130 μA max.	Aluminum-deposited surface, $I_F = 4$ mA, $V_{CE} = 2$ V, $d = 1$ mm (see note)
	Dark current	I_D 1 nA typ., 100 nA max.	$V_{CE} = 20$ V, 0 lx
	Leakage current	I_{LEAK} 500 nA max.	$I_F = 4$ mA, $V_{CE} = 2$ V, with no reflection
	Collector–Emitter saturated voltage	$V_{CE(sat)}$	---
	Peak spectral sensitivity wavelength	λ_P	930 nm typ.
Rising time	t_r	20 μs typ., 100 μs max.	$V_{CC} = 2$ V, $R_L = 1$ k Ω , $I_L = 100$ μA , $d = 1$ mm (see note)
Falling time	t_f	20 μs typ., 100 μs max.	$V_{CC} = 2$ V, $R_L = 1$ k Ω , $I_L = 100$ μA , $d = 1$ mm (see note)

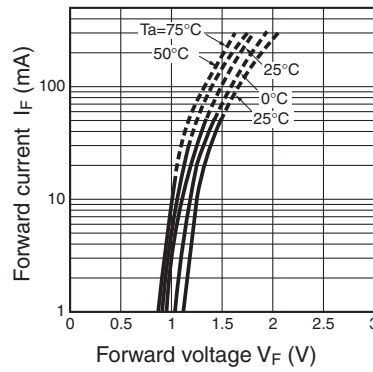
Note: Refer to the “Light Current Measurement Setup Diagram” in the Engineering Data section of this datasheet, regarding distance “d”.

■ Engineering Data

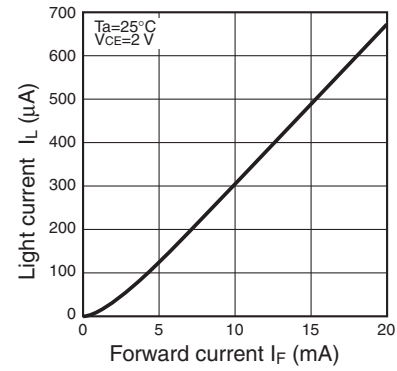
Forward Current vs. Collector Dissipation Temperature Rating



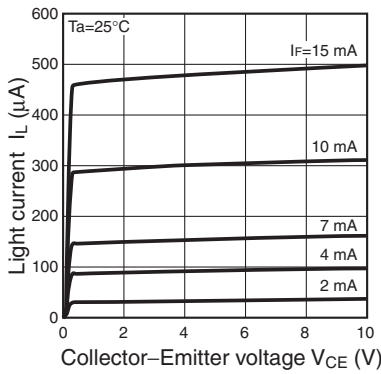
Forward Current vs. Forward Voltage Characteristics (Typical)



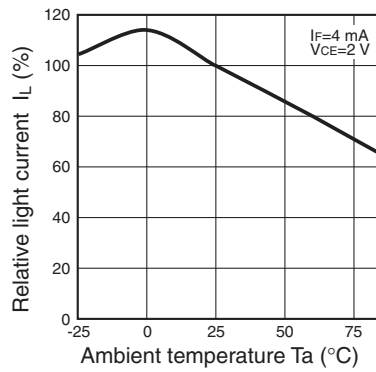
Light Current vs. Forward Current Characteristics (Typical)



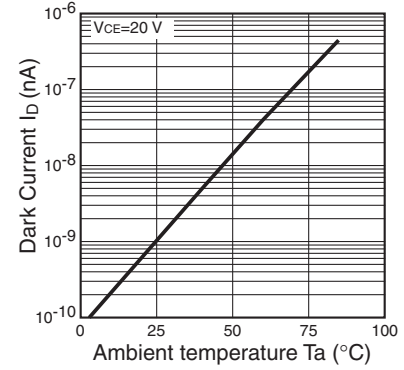
Light Current vs. Collector-Emitter Voltage Characteristics (Typical)



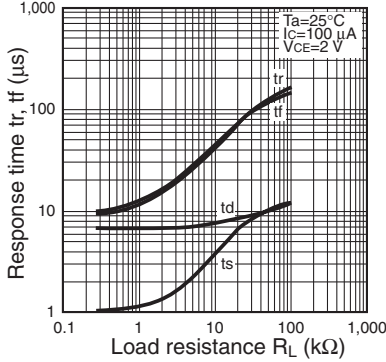
Relative Light Current vs. Ambient Temperature Characteristics (Typical)



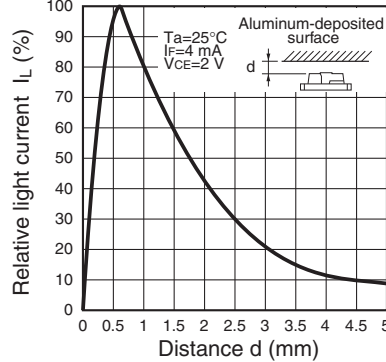
Dark Current vs. Ambient Temperature Characteristics (Typical)



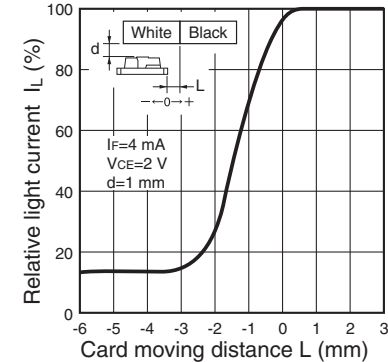
Response Time vs. Load Resistance Characteristics (Typical)



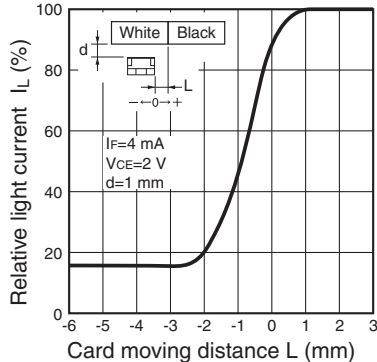
Sensing Distance Characteristics (Typical)



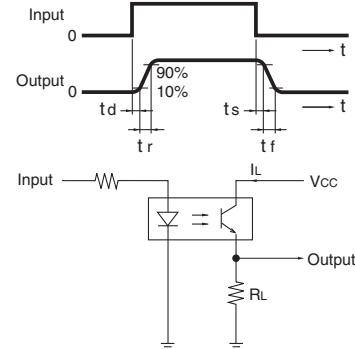
Sensing Position Characteristics (Typical)



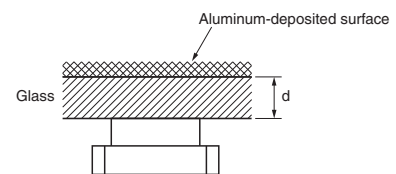
Sensing Position Characteristics (Typical)



Response Time Measurement Circuit



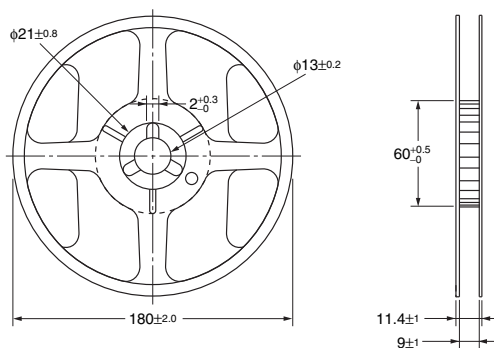
Light Current Measurement Setup Diagram



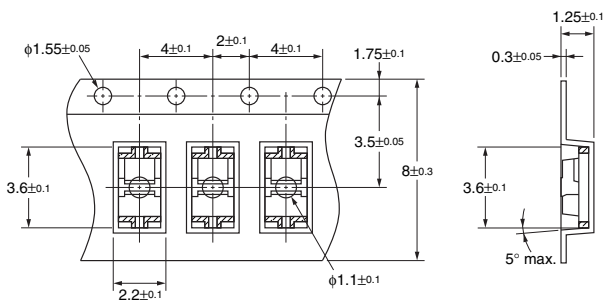
Unit: mm (inch)

■ Tape and Reel

Reel

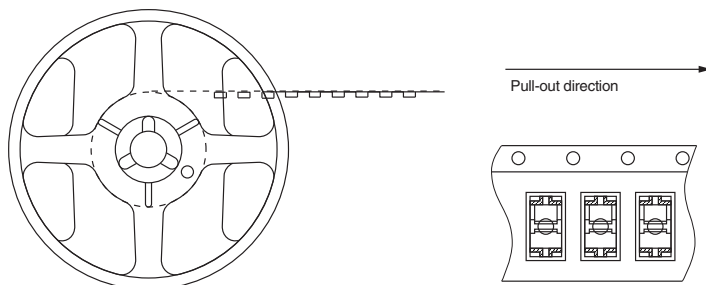


Tape



Tape configuration

The devices are oriented in the tape carrier so that the emitters are positioned closest to the carrier holes.



Tape quantity / packaging

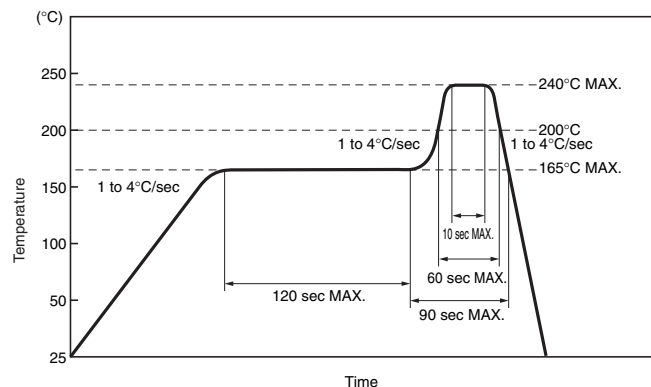
2,000 pcs./reel, with one reel sealed in an aluminum-laminated bag.

Precautions

■ Soldering Information

Reflow soldering

- Reflow no more than once.
- Adjust the amount of applied solder quantity to the product sidewall of the terminal
- When designing the pcb, avoid placing traces or other connections under the sensor, as shown in the 'Recommend Solder Pattern' diagram
- Set the reflow oven so that the temperature profile shown in the following chart is obtained for the upper surface of the product being soldered.



- Do not immerse the resin part of the sensor into the solder.
- The use of an infrared lamp can cause the temperature of the resin to rise too high. Test the soldering method under actual conditions and make sure that the process is acceptable, because the impact on the junction between the device and the PCB varies depending upon the soldering and cooling conditions.

Storage

Store the product under the following conditions:

Temperature: 5 to 30°C

Humidity: 70% max.

To protect the product from the effects of humidity until the package is opened, dry-box storage is recommended.

Reflow soldering must be done within 48 hours after opening the aluminum-laminated bag, during which time the product must be stored between 5°C and 25°C at 60% maximum humidity.

If it is necessary to store the product for more than 48 hours after opening the bag, use dry-box storage or reseal the products in the aluminum-laminated bag with a commercially available desiccant. Then, store the sensors between 5 to 30°C at 70% max. humidity, mounting them within 2 weeks.

Baking

If a product has remained packed in the aluminum-laminated bag for six months or more, or if more than 48 hours have lapsed since the bag was opened, then bake the product under the following conditions before use:

125°C for 16 to 24 hours (max.)

Note: Do not bake the sensors while they are still in their bag. Temporarily mount them to the PCB or place them in metal trays prior to baking. Subject the sensors to the baking process no more than once.

Cleaning Conditions

Recommended Solvents	Ethyl alcohol, methyl alcohol, or isopropyl alcohol
Solvent Temperature	45°C max
Immersion Time	3 hours max

Do not use ultrasonic cleaning.

A large grid of 20 columns and 30 rows of small squares, intended for taking notes. The grid is composed of thin, light gray lines forming a uniform pattern across the page.

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